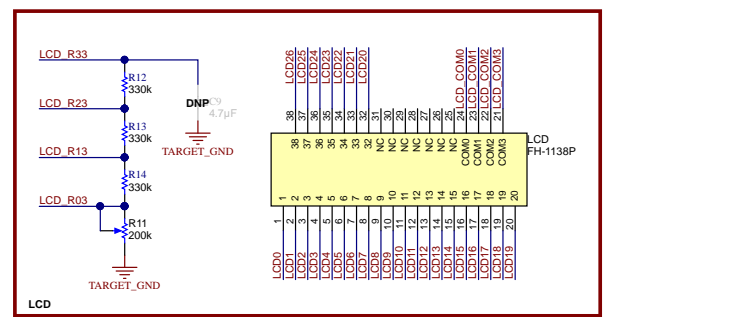
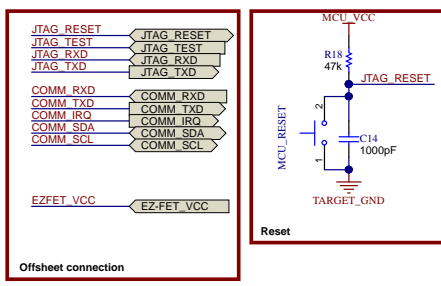
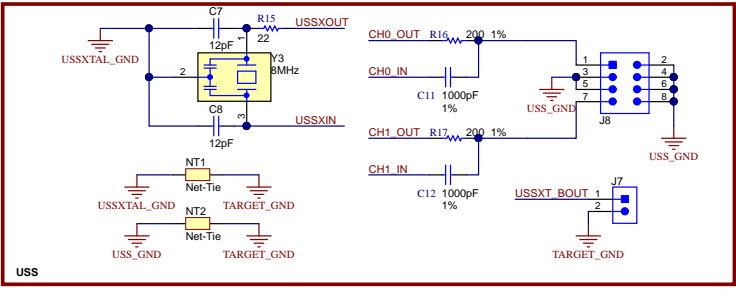
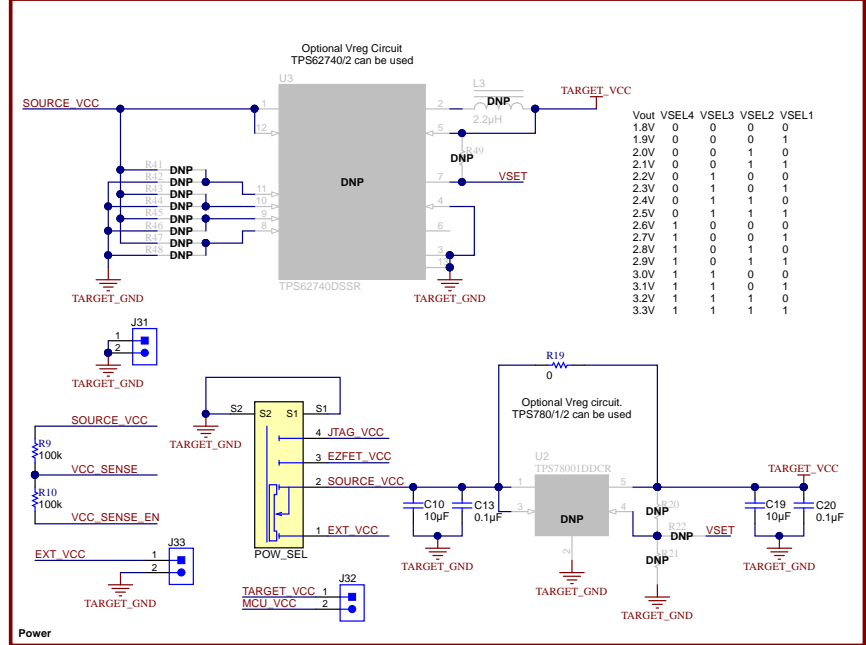
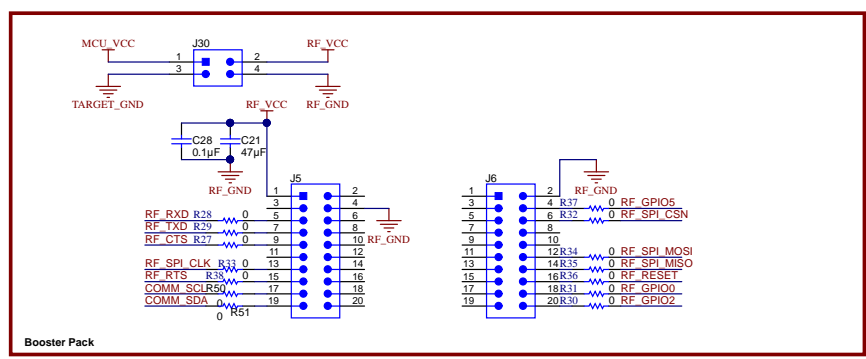
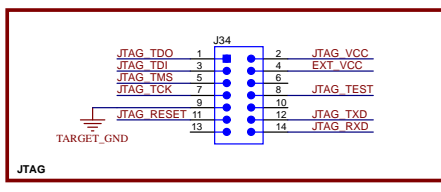
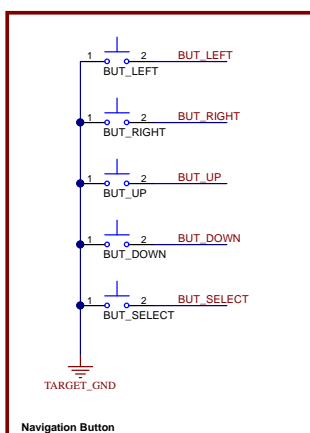
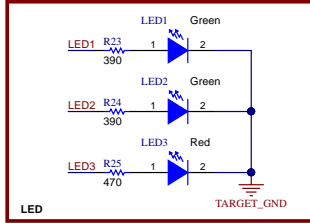
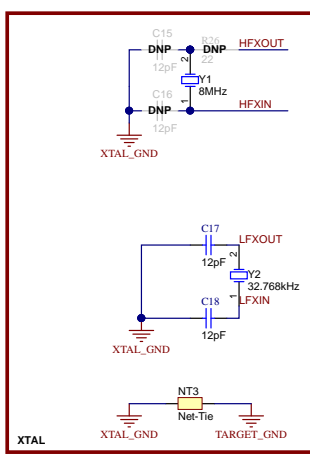
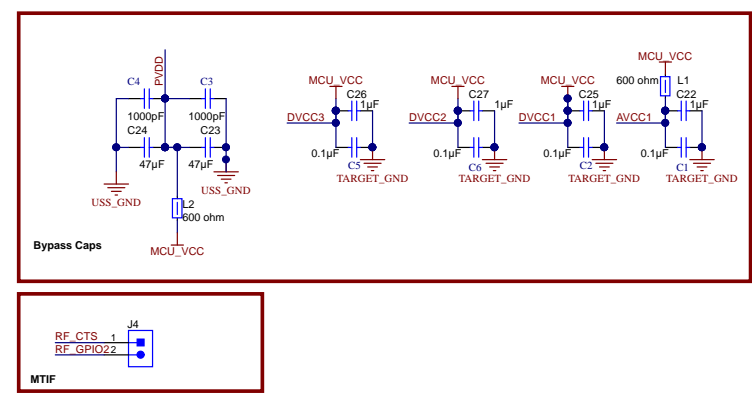
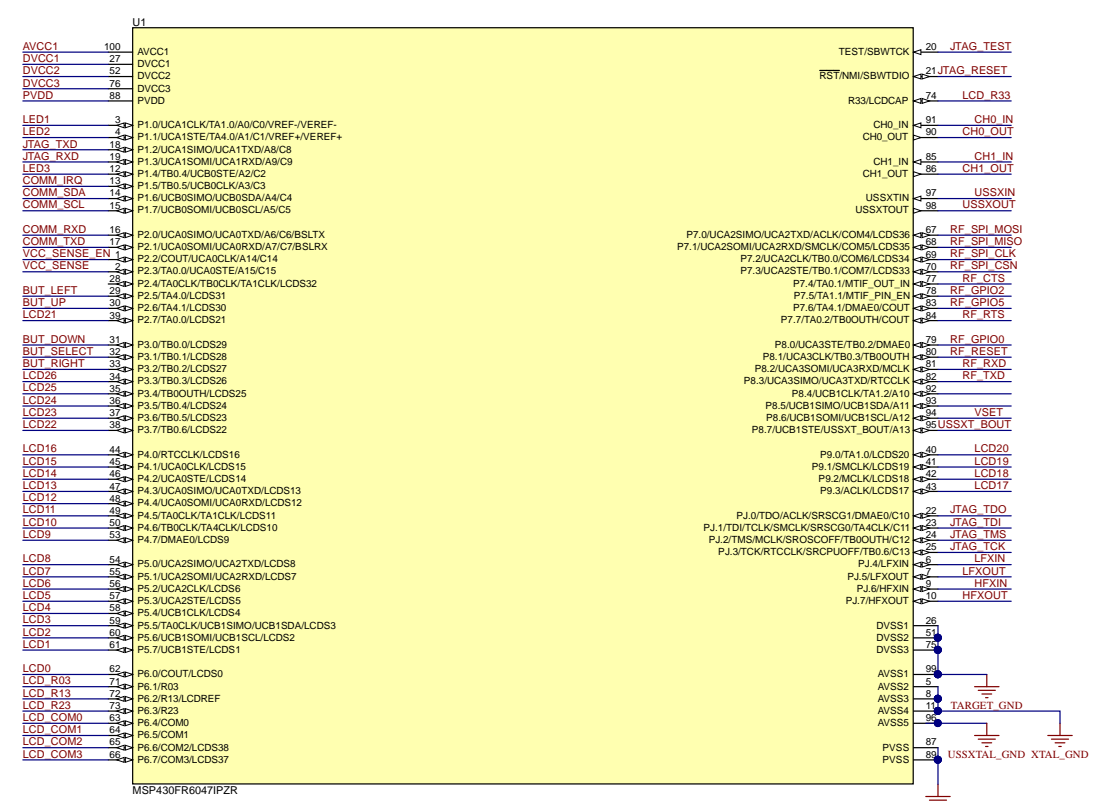


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Orderable: EVM430-FR6047	Designed for: Public Release	Mod. Date: 4/17/2018
TID #:	Project Title: EVM430-FR6047	
Number: MCU018	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 6
Drawn By:	File: MCU018A_Block.SchDoc	Size: B
Engineer: Eddie LaCost	Contact: http://www.ti.com/support	



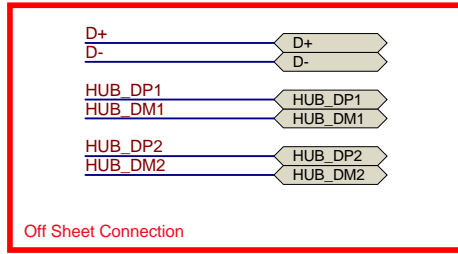
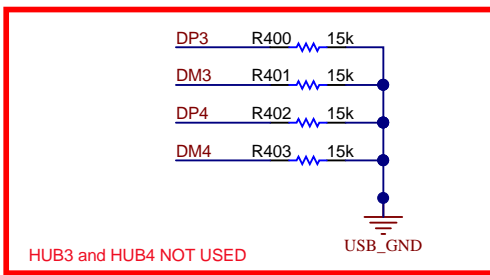
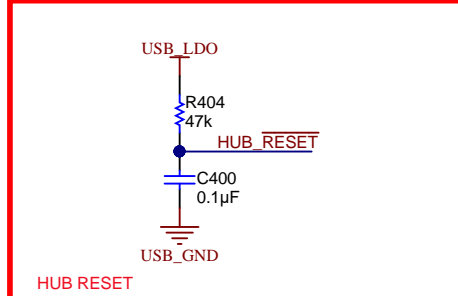
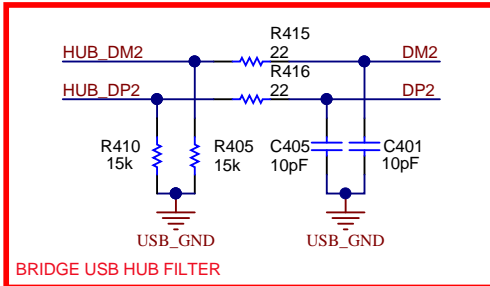
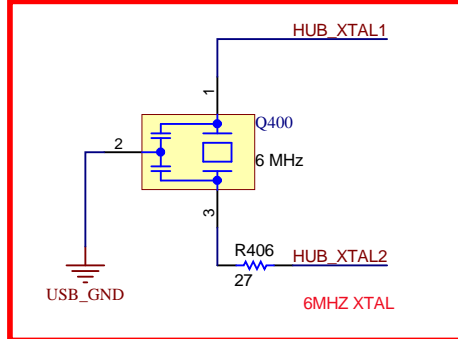
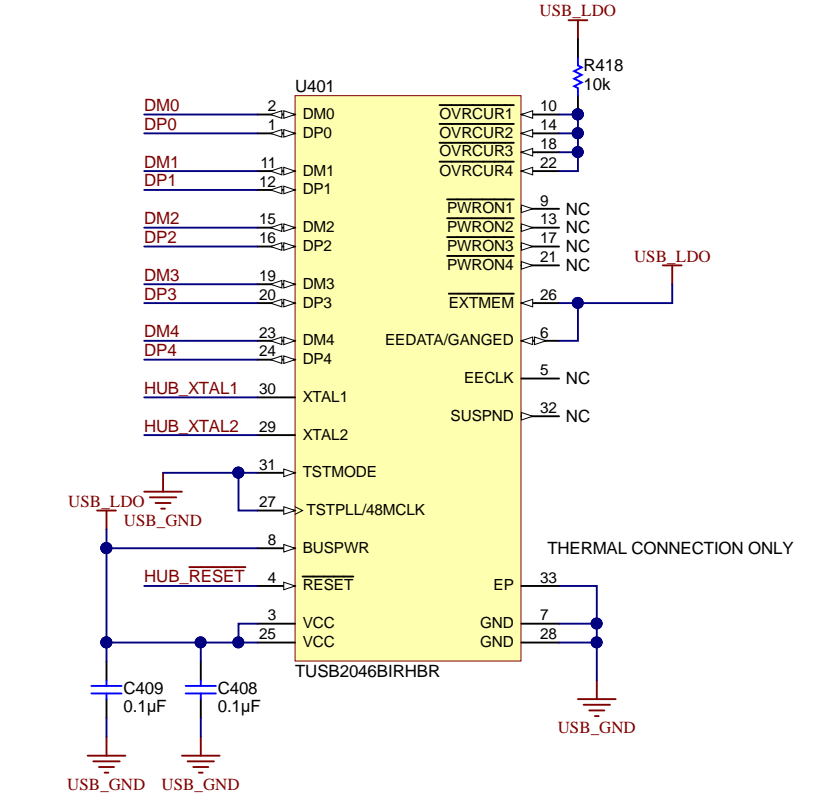
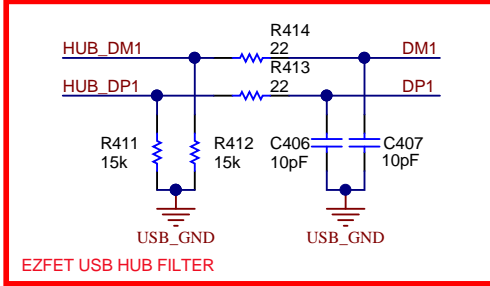
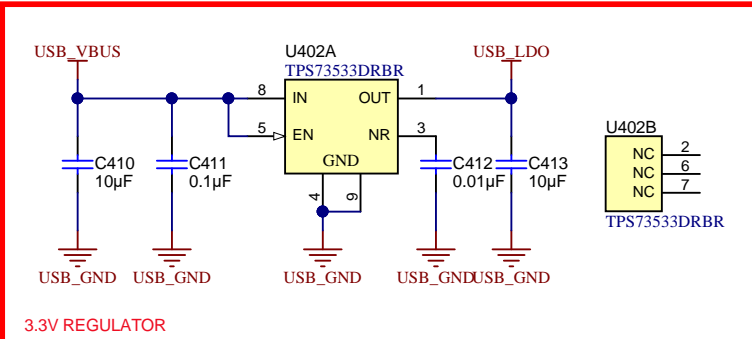
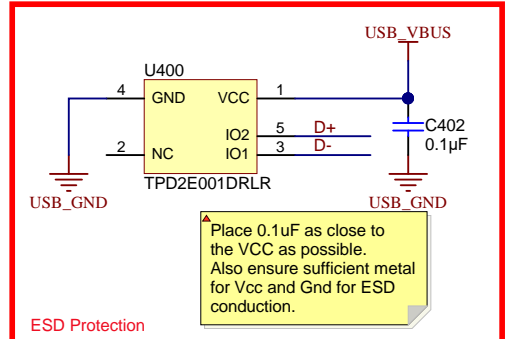
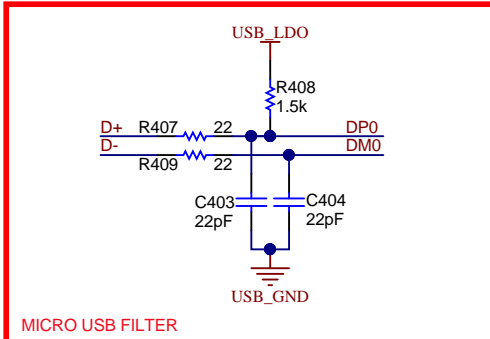


A

B

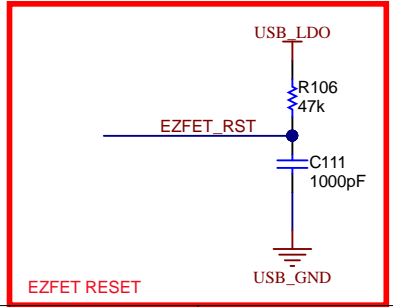
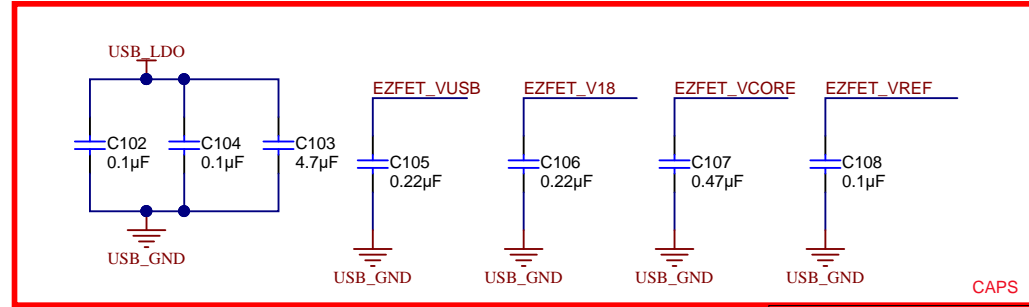
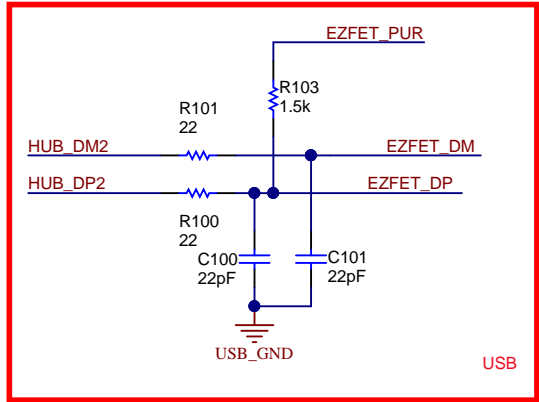
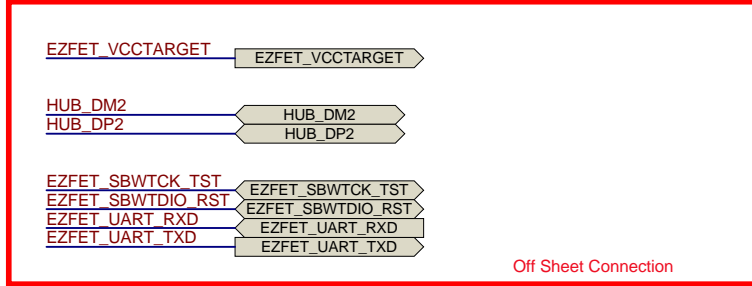
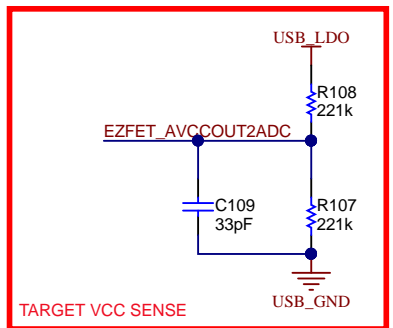
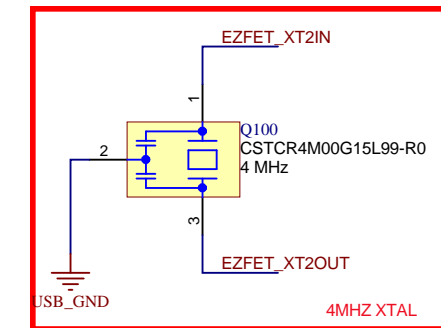
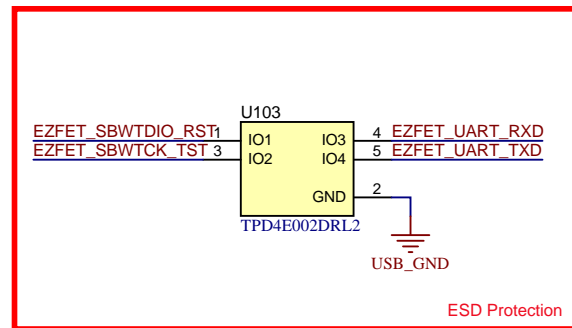
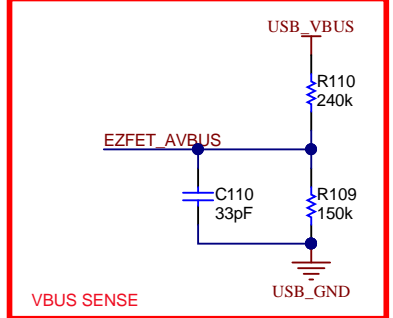
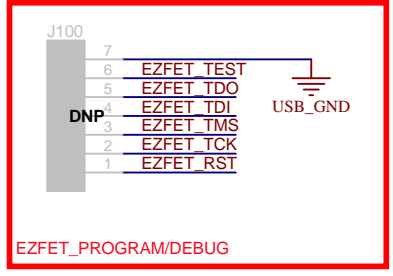
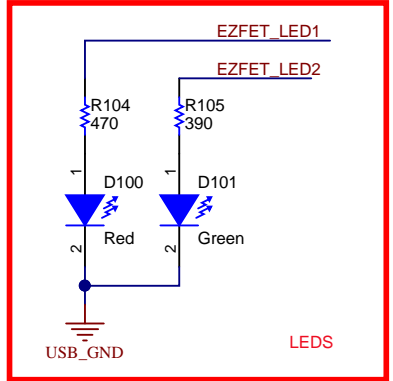
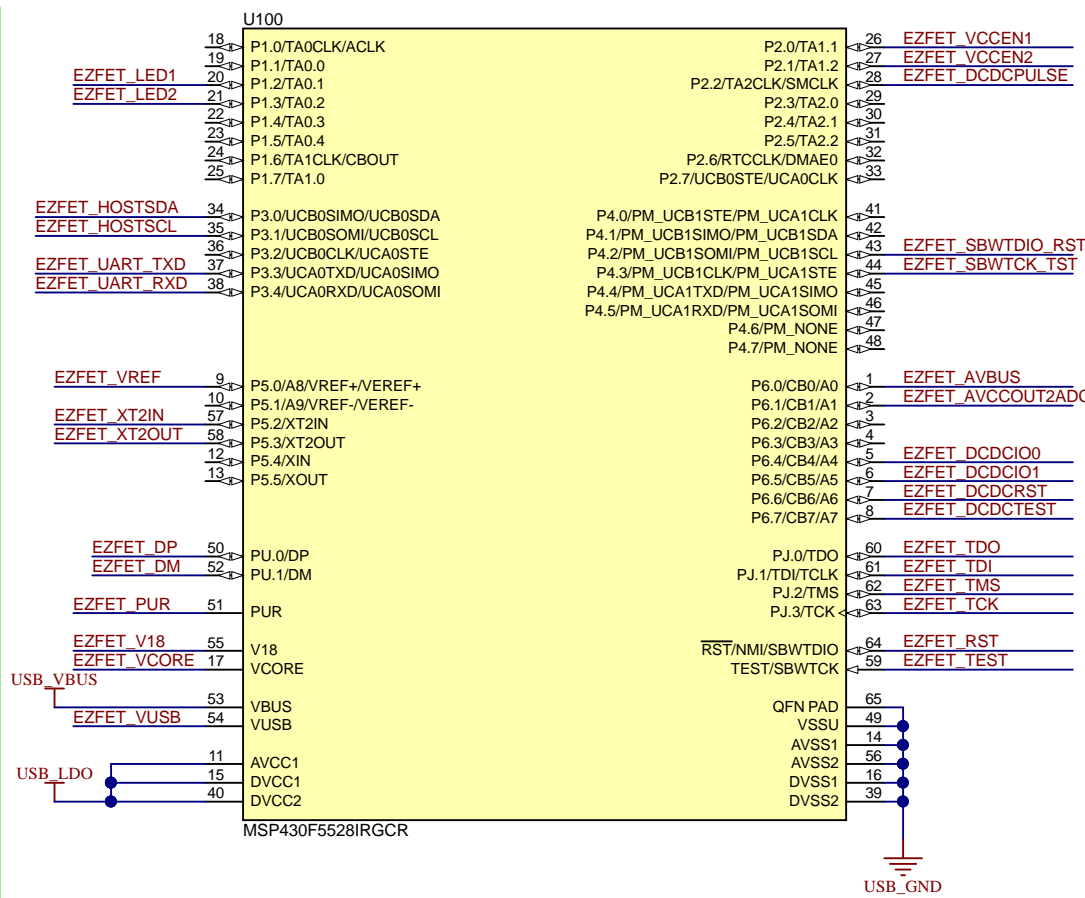
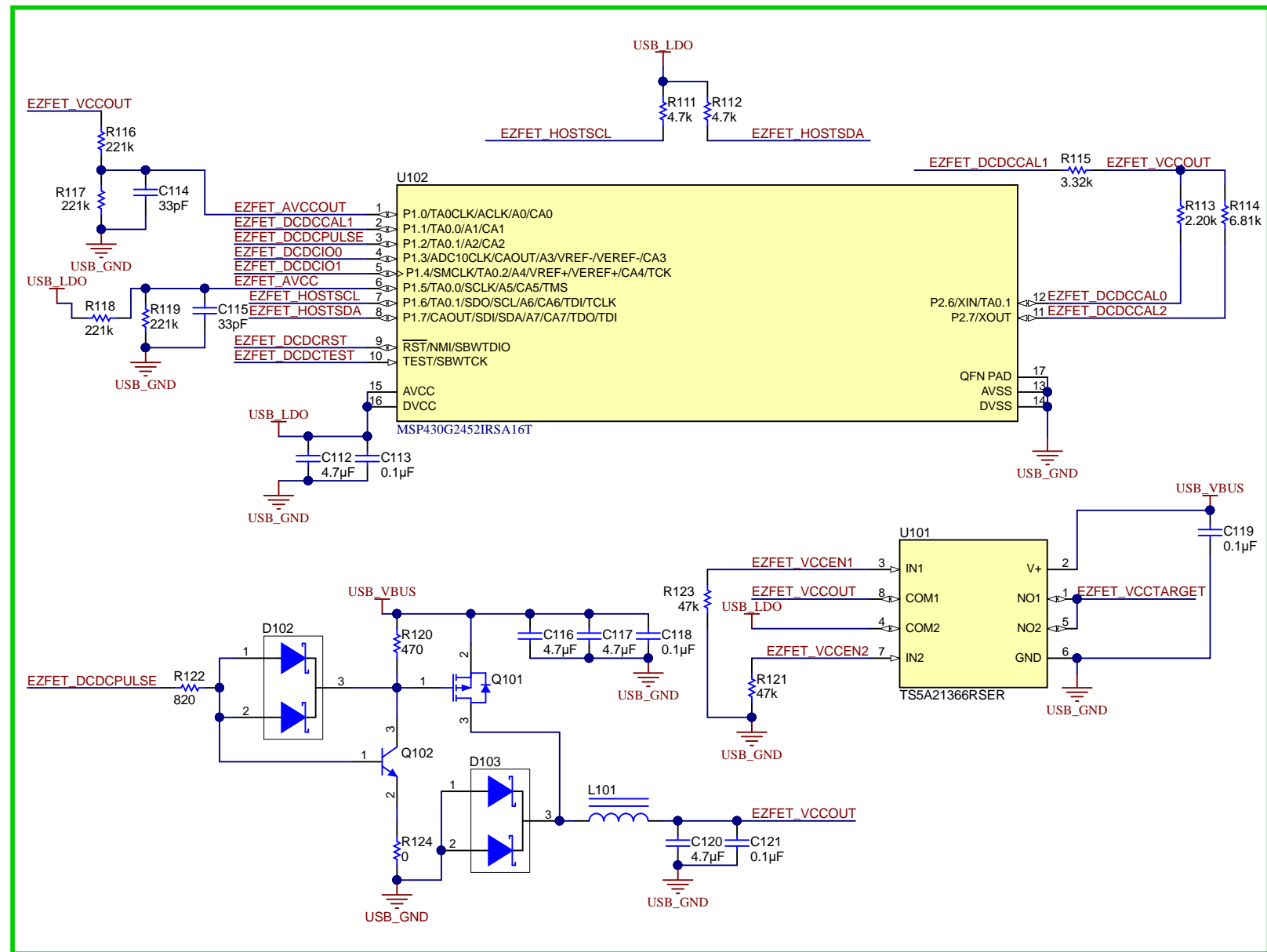
C

D

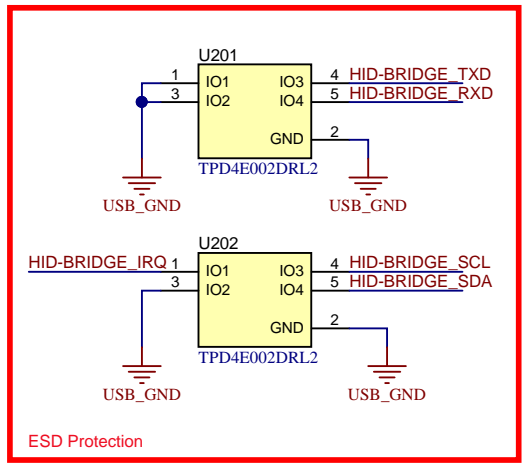
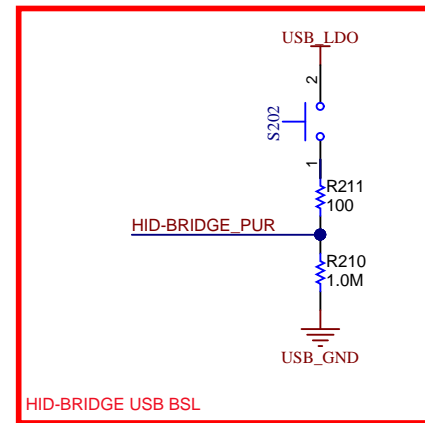
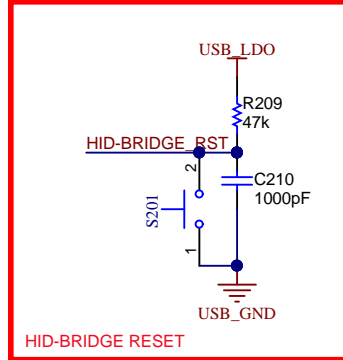
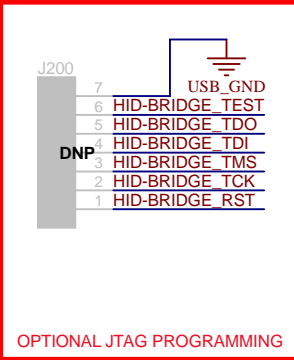
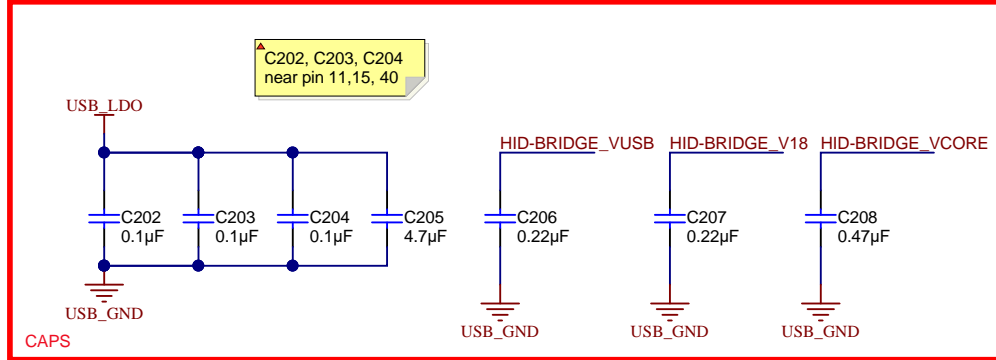


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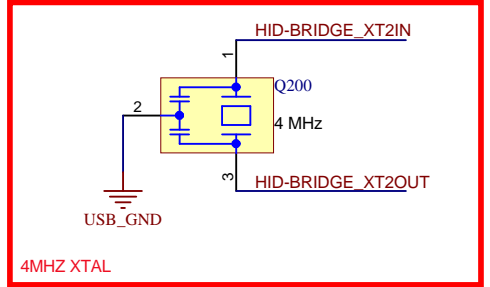
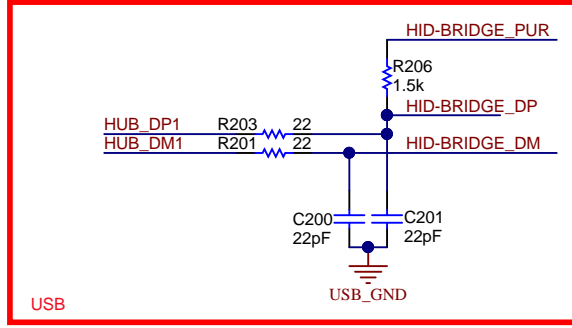
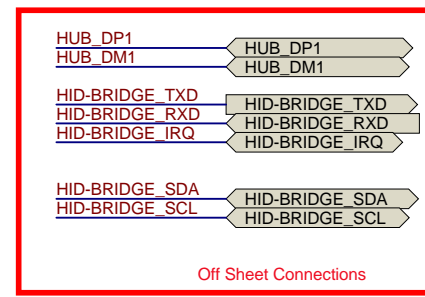
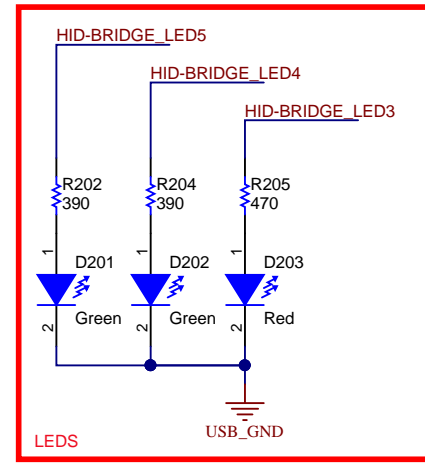
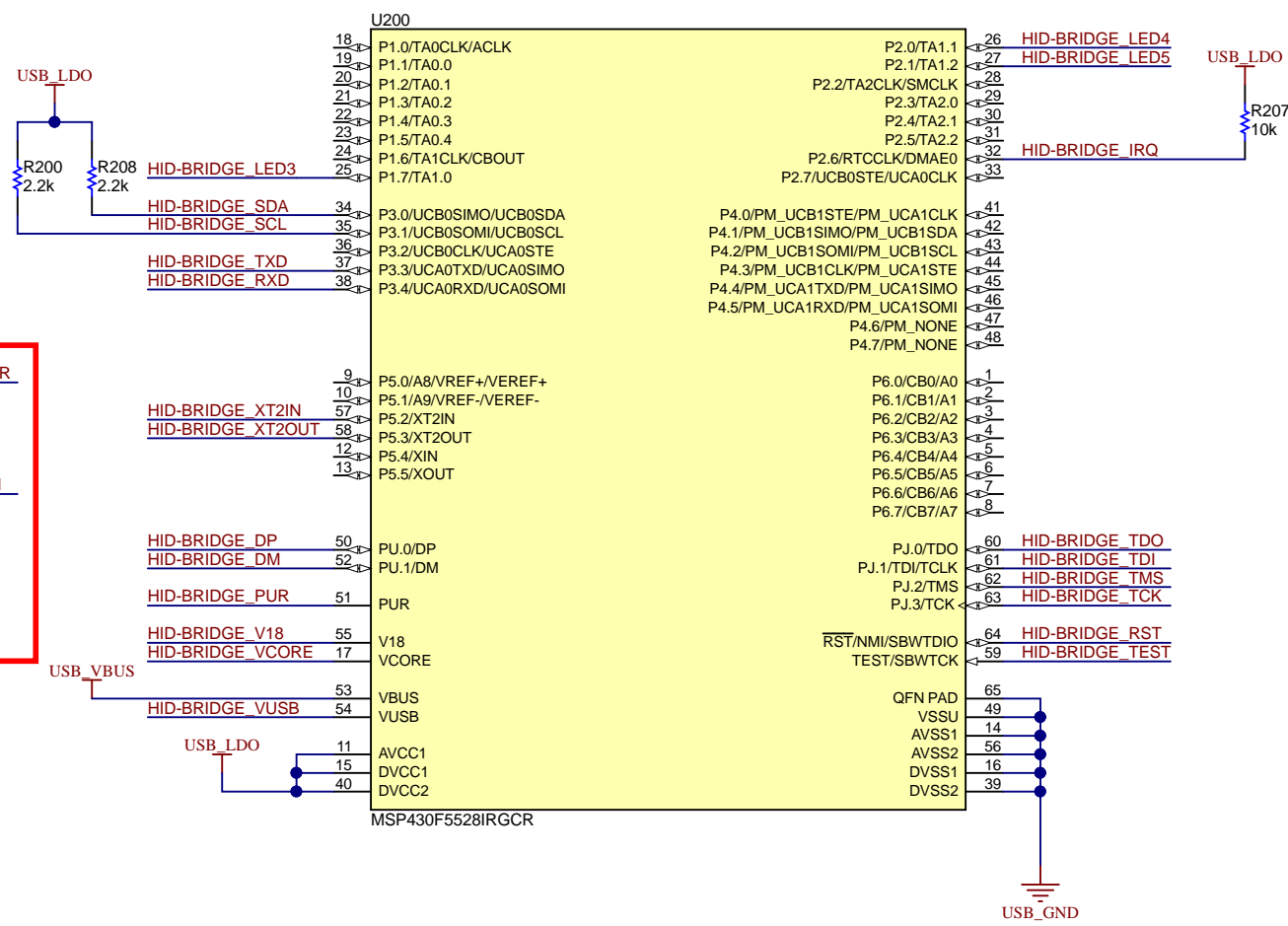
MSP430F5528 EZFET-LITE



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PCB Number: MCU018
PCB Rev: A

IPCB

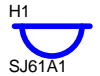
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Texas Instruments

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Logo2
PCB
LOGO
WEEE logo



LOGO4



H1
SJ61A1



H2
SJ61A1



H3
SJ61A1



H4
SJ61A1



FID1
DNP
Fiducial



FID2
DNP
Fiducial



FID3
DNP
Fiducial

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



SH-J1



SH-J2



SH-J3



SH-J4



SH-J5



SH-J6



SH-J7



SH-J8



SH-J9



SH-J10



SH-J11

Orderable: EVM430-FR6047	Designed for: Public Release	Mod. Date: 4/17/2018
TID #:	Project Title: EVM430-FR6047	
Number: MCU018	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 6 of 6
Drawn By:	File: MCU018A_Hardware.SchDoc	Size: B
Engineer: Eddie LaCost	Contact: http://www.ti.com/support	

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